IEC 60747-16-11

Edition 1.0 2026-04

INTERNATIONAL STANDARD

Semiconductor devices -
Part 16-11: Microwave integrated circuits - Power detectors

ICS 31.080.99

ISBN 978-2-8327-1178-1

IEC 60747-16-11:2026-04(en)

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Semiconductor devices - Part 16-11: Microwave integrated circuits - Power detectors

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IEC 60747-16-11 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47E/887/FDIS	47E/891/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

1 Scope

This part of IEC 60747 specifies the terminology, essential ratings and characteristics, and measuring methods of microwave integrated circuit power detectors.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60747-1:2006, *Semiconductor devices - Part 1: General*
IEC 60747-1:2006/AMD1:2010

IEC 60747-4:2007, *Semiconductor devices - Discrete devices - Part 4: Microwave diodes and* transistors
IEC 60747-4:2007/AMD1:2017

IEC 61340-5-1, *Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements*

IEC TR 61340-5-2, *Electrostatics - Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide*

Bibliography

IEC 60617, *Graphical symbols for diagrams* (available at http://std.iec.ch/iec60617)

IEC 60747-16-6:2019, *Semiconductor devices - Part 16-6: Microwave integrated circuits - Frequency multipliers*